Copper - HCP

Sheets



Material	Designation
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ASTM C10300

JIS C1030

INDIAN Cu-HCP

EN CW021A

BS -

Chemical Composition (%)

Cu ≥ 99.95

P 0.002 - 0.007

Applications

Telecommunication Cables
Power Distribution Systems
Cooling Elements
Electrical & Electronic Applications

Specification

Thickness 0.3 - 4 mm Width 350 - 1000 mm Length 400 - 6000 mm

Temper O, 1/4H, 1/2H, 3/4H, H, EH, SH

Properties

Formability Excellent
Welding Ability Good
Electrical Conductivity Good
Thermal Conductivity Good

Description

Cu-HCP is a high purity, high conductivity, low phosphorus Copper. This copper may be heat treated, welded and brazed without need for special precautions to avoid hydrogen embrittlement. HCP copper is alloyed with small amount 20 - 70 ppm of phosphorous. This small quantity of phosphorous will not reduce significantly the electrical and thermal conductivity of the alloy but help to obtain homogenous grain size in the product.

Value Proposition

- Competitive Pricing
- Flexible LME price fixation
- Product Customization

- Quality Assurance
- Committed to deliveries
- Standard export pallet packing

This data is general technical specification; Binding technical specifications will be as per agreement.

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